



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Adrian E. Ong
Title: Layout And Use Of Bond Pads And Probe Pads For
Testing Of Integrated Circuits Devices
Application No.: 10/003,375
Filing Date: November 15, 2001
Examiner: Tung X. Nguyen
Group Art Unit: 2829
Confirmation No.: 4697
Law Office: Sidley Austin Brown & Wood LLP
Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

This is a Response to the Final Office Action dated August 24, 2005 for the above-referenced Application. Applicant respectfully requests reconsideration of the Application in view of the following amendments and remarks.